

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions,
and listings, of claims in the application:

LISTING OF CLAIMS:

1. (currently amended) A silicon containing curing composition comprising:

at least one silicon containing polymer selected from the group consisting of: component (A) [,] and component (B) ~~and component (C), provided that the composition contains both the components (A) and (B) when the component (C) is absent;~~ and component (D) a catalyst,

wherein,

said composition is applicable to the electrical and electronic field as a sealing compound;

component (A) is a silicon containing polymer, which comprises:

at least one kind of a reactive group A' selected from the group consisting of Si-R¹, Si-O-R², and Si-R³-OCOC(R⁴)=CH₂, wherein R¹ and R² each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group, R³ represents an alkylene group having 1 to 9 carbon atoms and/or an arylene group, and R⁴ represents hydrogen or a methyl group,

an Si-O-Si bridge structure formed from at least one site thereof, and

20% by weight or less of a component whose weight average molecular weight is 1000 or less;

component (A) is obtained by reacting silicon containing polymer precursors with each other which are obtained by a sol gel process using one of the silicon containing polymer precursors is a linear polysiloxane compound and:

an alkoxy silane and/or chlorosilane having the reactive group A', and/or

an alkoxy silane and/or chlorosilane having no reactive group A';

component (B) is a silicon containing polymer, which comprises:

an Si-H group,

an Si-O-Si bridge structure formed from at least one site thereof, and containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less,

provided that said Si-H group is introduced into the polymer, which is formed by hydrolyzing and condensing an alkoxy silane and/or a chlorosilane, each having no Si-H group, using a reactive functional group Si-OH and/or a reactive functional group Si-Cl;

~~component (C) is a silicon containing polymer, which comprises:~~

at least one kind of a reactive group A' selected from the group consisting of Si R^1 , Si O R^2 , and $\text{Si R}^3 \text{OCOC(R}^4\text{)=CH}_2$, wherein R^1 and R^2 each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group, R^3 represents an alkylene group having 1 to 9 carbon atoms and/or an arylene group, and R^4 represents hydrogen or a methyl group, and

an Si H group,

an Si O Si bridge structure formed from at least one site thereof, and

-20% by weight or less of a component whose weight average molecular weight is 1000 or less,

provided that said Si H group is introduced by allowing a chlorosilane and/or a silanol, each having an Si H group to react with an Si OH Si OH group and/or an Si Cl group left after a sol gel reaction of alkoxysilane and/or chlorosilane, each having no Si H group;

component (D) is a platinum-based catalyst;

the total aryl group and arylene group content of the total silicon containing polymers as components (A) [[,]] and (B), and (C) is 1% to 25% by weight; and

the components (A) [[,]] and (B), and (C) each have a weight average molecular weight of 5,000 to 1,000,000.

2. (cancelled)

3. (previously presented) The silicon containing curing composition according to claim 1, further comprising a fine metal oxide powder as component (E).

4. (previously presented) A cured product obtained by heat curing the silicon containing curing composition according to claim 1.

5. (cancelled)

6. (previously presented) The silicon containing curing composition according to claim 1, wherein the bridge structure is a configuration selected from the group consisting of a ladder configuration, a cage configuration and a cyclic configuration.

7. (cancelled)

8. (previously presented) The silicon containing curing composition according to claim 1, wherein the composition has a viscosity of 2 to 50 Pa·s at 25°C.

9. (previously presented) The silicon containing curing composition according to claim 1, wherein the ratio of the total aryl group and arylene group content of the component (A) to the

total aryl group and arylene group content of the component (B) is 0.5 to 1.5:0.5 to 1.5 by weight.